

Title: Three-Dimensional Electrical Device Packaging Employing Low Profile
Elastomeric Interconnection
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ABSTRACT

A compliant interconnect for compactly, releasably packaging vertically-spaced electrical devices. The compliant interconnect includes at least one substrate for supporting and electrically connecting to the electrical devices, a layer of anisotropic conductive elastomer (ACE) between each electrical device and each immediately adjacent electrical device, and a layer of ACE between the substrate and the electrical device closest to the substrate. The ACE layers provide electrical connection through the package, and also conduct heat from the electrical devices. There is also a device that applies a compressive load to each of the ACE layers

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